

## Welcome to O-leading

We are professional PCB manufacturer with more than ten years experiences . Products range-single, double side ,multi-layer PCB ,flexible PCB and MCPCB.We can provide fast prototype service - S/S in 24hrs , 4-8layers in 48-96 working hrs production time.

COPPER PLATE HOLES MINIMUM .025 AVG, .020 MIN.. HOLES MAY NOT BE PLUGGED

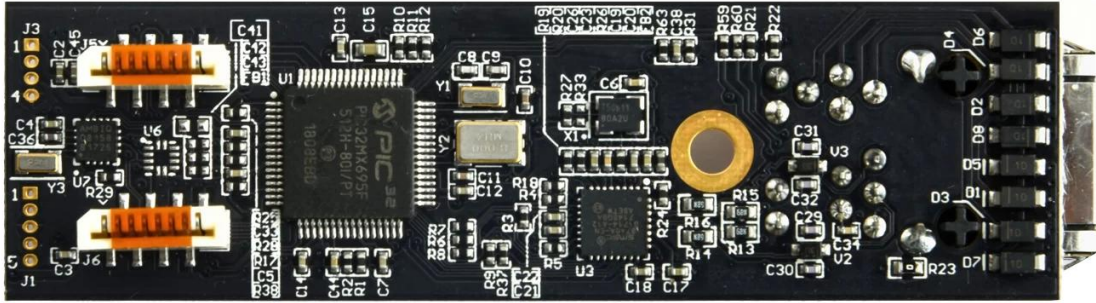
Pack with colorless transparent bubble film ,25 PCS/ bag, put desiccant in flank, put humidity indicator card on top side

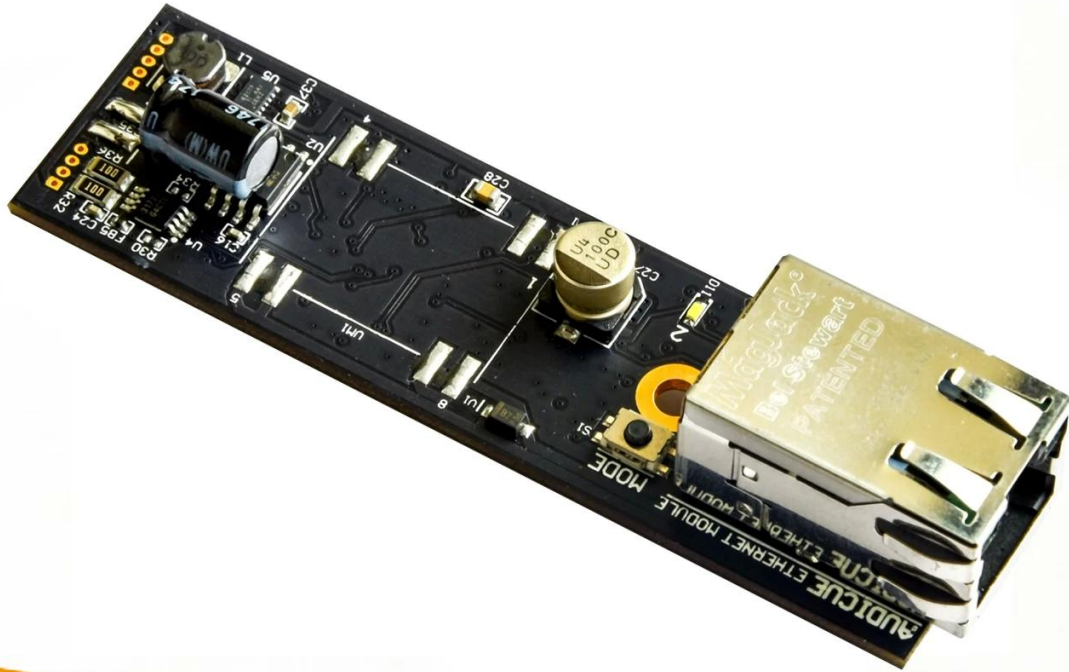
PLEASE CLICK THESE FOR MORE INFORMATION [Engine Power Module manufacturer china](#)

## Product Description

PCB P/N	T002_EthModule
Layer Count	4L
Material	FR-4 TG135
Board thk	1.6mm
copper thk	1/1/1/1oz
Smallest hole size	0.3MM
No. of holes (pcs)	218
line w/s	5/5mil
Impedance control. Y / N (Tol %)	Y / 100+/-10%Ω
Surface Finishing:Plated hard Gold, Au	0.05-0.10UM
Solder Mask Silkscreen	Blue / White
Single board size	Dim X (mm):80;Dim Y (mm):22.6
Panelisation	Dim X (mm):90;Dim Y (mm):121;No Of UPS:5
Special:peelable mask	N
Routing/Punching	CNC+V-CUT







[www.o-leading.com](http://www.o-leading.com)

[Immersion Tin supplier china](#)

Our Team







Certifications



**QUALITY MANAGEMENT SYSTEM CERTIFICATE**  
 Certificate No: 16118Q10347R05

**We hereby certify that**  
**O-LEADING SUPPLY CHAIN(HK) CO.,LIMITED**  
 Credit No: 61691591-000-07-17-2  
 Registration Add: ROOM 603D 6/F HANG PONT COMMERCIAL BUILDING,31 TONKIN ST,CHEUNG SHA WAN,KL, HK  
 Business Add: 1313 Floor 13 Fortune Building, Danshui Town, Huiyang District, Huizhou, Guangdong, China

Has implemented and maintains a **Quality Management System**  
 Which fulfills the requirements of the following standards  
**GB/T19001-2016 idt ISO9001:2015**

**Scope of certification**  
 Sales of printed circuit boards

Initial Issuance period: February 27, 2018  
 This certificate is valid during: February 27, 2018 -- February 26, 2021  
 This certificate is invalid without CICC qualified label in the following period

First supervision and audit	Qualified mark	Second supervision and audit	Qualified mark
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The certification registration scope shall include the product/service scope which fall to be covered by the relevant effective administrative permission and qualification permission required by the state. The effectiveness of this certificate shall be evaluated by annual surveillance audit of CICC. The certificate shall be valid when used together with the surveillance audit conclusion. The related information of this certification can be searched at the public website of company www.cicc.com.cn.

**CICC IAF CNAS**

201726 201VZL430354 - Wiring, Printed - Component

**UL ONLINE CERTIFICATIONS DIRECTORY**

**ZPMV2.E490354**  
**Wiring, Printed - Component**

For enhanced search functionality, please visit [UL.com](http://ul.com) Family of Databases. Click on a product designation for complete information.  
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**Wiring, Printed - Component**

[See General Information for Wiring, Printed - Components](#)

**O-LEADING SUPPLY CHAIN CO LIMITED** E490354

Fortune Building, Nanheng West Road  
 Room 1313  
 Huizhou, Guangdong 516211, CHINA

Cond Width				Max		Max					
Min	Edge	Cond	SS/Thk	Area DS/ Diam	Solder Limits	Dper	Temp	Flame	RoHS	C	T
Typ	max(in)	mm(in)	mic(mil)	DSO	mm(in)	C	sec	C	Class	DSR	I
<b>Multi-layer (mass laminate) printed wiring boards.</b>											
<b>O-LEADING-401</b>											
	0.2 (0.004)	0.3 (0.012)	34 (1.34)	D6	12.7 (0.5)	260	10	130	V-0	-	-
<b>O-LEADING-407</b>											
	0.08 (0.003)	0.2 (0.008)	17 (0.67)	D5	9.2 (0.4)	260	10	170	V-0	NI	-
<b>Multi-layer printed wiring boards.</b>											
<b>O-LEADING-408</b>											
	0.125 (0.005)	0.125 (0.005)	12 (0.47) 31-135	D6	50.8 (2.0)	260	20	130	V-0	NI	1
<b>Single layer printed wiring boards.</b>											
<b>O-LEADING-002</b>											
	0.76 (0.03)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	105	V-0	NI	-
<b>O-LEADING-003</b>											
	0.38 (0.015)	1.14 (0.045)	34 (1.34)	S5	19.1 (0.8)	260	10	130	V-0	▲	-
<b>O-LEADING-033</b>											
	0.15 (0.006)	0.3 (0.012)	34 (1.34)	S5	25.4 (1.0)	260	10	120	V-0	NI	-
<b>O-LEADING-205</b>											
	0.1 (0.004)	0.3 (0.012)	34 (1.34)	D6	69.6 (2.7)	260	10	130	V-0	NI	-
<b>O-LEADING-206</b>											
	0.15 (0.006)	0.33 (0.013)	17 (0.67)	D5	69.6 (2.7)	260	10	130	V-0	NI	-

\* - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.  
 Last updated on 2017-01-27

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<http://www.ul.com/onlinecertificationsdirectory/201VZL430354-Wiring,Printed-Component> 10



**Test Report** No. CAVEC1805164701 Date: 03 Apr 2018 Page 2 of 8

Test Results:

Test Part Description:

**Specimen No.** **SGS Sample ID** **Description**  
 SN1 CAN18-051647.001 Green PCB\*

Remarks:

- (1) 1 mg/kg = 1 ppm = 0.0001%
- (2) MDL = Method Detection Limit
- (3) ND = Not Detected (< MDL)
- (4) "-" = Not Regulated

**RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU**

Test Method: With reference to IEC 62321-4:2014+A1:2017, IEC 62321-5:2013, IEC 62321-7-2:2017, IEC 62321-6:2015 and IEC 62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	Det
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	9
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (CrVI)	1,000	mg/kg	8	ND
Sum of PBBs	1,000	mg/kg	-	ND
Mono-bromobiphenyl	-	mg/kg	5	ND
Dibromobiphenyl	-	mg/kg	5	ND
Tribromobiphenyl	-	mg/kg	5	ND
Tetrabromobiphenyl	-	mg/kg	5	ND
Pentabromobiphenyl	-	mg/kg	5	ND
Hexabromobiphenyl	-	mg/kg	5	ND
Heptabromobiphenyl	-	mg/kg	5	ND
Octabromobiphenyl	-	mg/kg	5	ND
Nonabromobiphenyl	-	mg/kg	5	ND
Decabromobiphenyl	-	mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg	-	ND
Mono-bromodiphenyl ether	-	mg/kg	5	ND
Dibromodiphenyl ether	-	mg/kg	5	ND
Tribromodiphenyl ether	-	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether	-	mg/kg	5	ND



SGS shall not be held responsible for any consequences arising from the use of the information provided in this report. The information provided in this report is for reference only and does not constitute a warranty. The information provided in this report is for reference only and does not constitute a warranty. The information provided in this report is for reference only and does not constitute a warranty.

Member of the SGS Group (SGS SA)



## Packaging & Delivery

Packaging Details	16 years professional OEM pcb board manufacturer
Delivery Detail	7-12days

☐ **GOLDEN FINGER BOARD** supplier ☐



## FAQ

1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

- 1.The process is strictly controlled under ISO 9001:2008 standards.
- 2.Extensive use of software in managing the production process
- 3.State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 4.Dedicated quality assurance team with failure case analysis process
- 5.Continuous staff training and education

2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly. However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edge on cost and quality.



3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

4. What data are needed for PCB production?

It is best to provide data in Gerber 274-X format. In addition, Cam350, CAD, Protel 99se, PADS, DXP and Eagle can also be processed.

5. What's the typical process flow for multi-layer PCB?

Material cutting → Inner dry film → inner etching → Inner AOI → Multi-bond → Layer stack up  
Pressing → Drilling → PTH → Panel Plating → Outer Dry Film → Pattern Plating → Outer etching →  
Outer AOI → Solder Mask → Component Mark → Surface finish → Routing → E/T → Visual Inspection.